

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	467861	(stck stackable stacking stacked plurality multi multiple) with (semiconductor chip die dice ic (integrated adj circuit) compoenent electronic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:55
L2	481872	(stack stackable stacking stacked plurality multi multiple) with (semiconductor chip die dice ic (integrated adj circuit) compoenent electronic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:55
L3	745051	(stack stackable stacking stacked plurality multi multiple) with (semiconductor chip die dice ic (integrated adj circuit) component electronic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:56
L4	1890978	(stack stackable stacking stacked plurality multi multiple lower upper first second) with (semiconductor chip die dice ic (integrated adj circuit) component electronic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:57
L5	269691	4 same ((plurality multi multiple lower upper first second) with (pad electrode terminal))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:58
L6	237462	4 with ((plurality multi multiple lower upper first second) with (pad electrode terminal))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:58
L7	20273	(package packaging packaged) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 09:59
L8	7636	(wire trace redistribute redistribution redistributed redistributing) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:00

L9	345	(offset stag stagger staggering staggered off cascade cascading cascaded) same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:24
L10	1	"6552426".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:11
L11	1	"6445075".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:12
L12	1	"6353312".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:12
L13	1	"6323663".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:12
L14	1	"6291884".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:12
L15	1	"6291884".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:12
L16	1	"6239496".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:12
L17	1	"6144101".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:13
L18	1	"6133638".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L19	1	"6133638".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L20	1	"5701666".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L21	1	"5677575".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L22	1	"5571027".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L23	1	"5440241".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L24	1	"5397997".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L25	1	"5258648".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:14
L26	1	"5397997".PN.	USPAT; USOCR	OR	OFF	2005/11/05 10:15
L27	7291	8 not 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:23

L28	2599	(offset stag stagger staggering staggered off cascade cascading cascaded) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:24
L29	2254	28 not 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:24
L30	2158	(inter surface intersurface pattern) and 29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:26
L31	7441994	(leadframe frame lead substrate carrier board pcb ((printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:27
L32	2145	30 and 31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 10:27
L33	1960	(expose exposing exposed extending extend extended extension overhang) and 32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 11:08
L34	1782	33 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 12:05
L35	2	"20020140107"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 12:05

L36	1	35 and (leadframe (lead adj frame))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 12:05
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